



## Global Ultrasonic Wafer Inspection Equipment Market Research Report 2026

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## 内容摘要

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The global Ultrasonic Wafer Inspection Equipment market was valued at US\$ million in 2025 and is anticipated to reach US\$ million by 2032, at a CAGR of %from 2026 to 2032.

The 2025 U.S. tariff policies introduce profound uncertainty into the global economic landscape. This report critically examines the implications of recent tariff adjustments and international strategic countermeasures on Ultrasonic Wafer Inspection Equipment competitive dynamics, regional economic interdependencies, and supply chain reconfigurations.

Ultrasonic wafer inspection equipment is a special equipment that uses ultrasonic technology to detect surface and internal defects on wafers. By sending an ultrasonic signal and measuring how and how fast it propagates through the wafer, cracks, bubbles, foreign objects and other defects in the wafer can be detected.

The North American market for Ultrasonic Wafer Inspection Equipment is projected to increase from US\$ million in 2025 to US\$ million by 2032, at a CAGR of % over 2026–2032.

The Asia-Pacific market for Ultrasonic Wafer Inspection Equipment is projected to rise from US\$ million in 2025 to US\$ million by 2032, at a CAGR of % over 2026–2032.

Major global manufacturers of Ultrasonic Wafer Inspection Equipment include Sonix, Nidec-Read, KLA Corporation, Hitachi High-Tech, TDK Corporation, EAG Laboratories, Applied Materials, Nanometrics, Bruker Corporation, Intego GmbH, etc. In 2025, the world's top three vendors accounted for approximately % of revenue.

This report delivers a comprehensive overview of the global Ultrasonic Wafer Inspection Equipment market, with both quantitative and qualitative analyses, to help readers develop growth strategies, assess the competitive landscape, evaluate their position in the current market, and make informed business decisions regarding

Ultrasonic Wafer Inspection Equipment. The Ultrasonic Wafer Inspection Equipment market size, estimates, and forecasts are provided in terms of shipments (K Units) and revenue (US\$ millions), with 2025 as the base year and historical and forecast data for 2021–2032.

The report segments the global Ultrasonic Wafer Inspection Equipment market comprehensively. Regional market sizes by Type, by Application, , and by company are also provided. For deeper insight, the report profiles the competitive landscape, key competitors, and their respective market rankings, and discusses technological trends and new product developments.

This report will assist Ultrasonic Wafer Inspection Equipment manufacturers, new entrants, and companies across the industry value chain with information on revenues, production, and average prices for the overall market and its sub-segments, by company, by Type, by Application, and by region.

#### Market Segmentation

##### By Company

- Sonix
- Nidec-Read
- KLA Corporation
- Hitachi High-Tech
- TDK Corporation
- EAG Laboratories
- Applied Materials
- Nanometrics
- Bruker Corporation
- Intego GmbH
- ECHO Ultrasonics
- Olympus Corporation
- Ultrasonic Sciences Ltd
- GE Inspection Technologies

##### Segment by Type

- Handheld
- Desktop

##### by Application

- Electronics Industry
- Business Area
- Others

##### Production by Region

- North America
- Europe
- China
- Japan

##### Consumption by Region

- North America
- U.S.
- Canada
- Asia-Pacific
- China
- Japan
- South Korea
- China Taiwan
- Southeast Asia
- India
- Australia
- Rest of Asia
- Europe
- Germany
- France
- U.K.
- Italy
- Russia
- Rest of Europe
- Latin America, Middle East & Africa
- Mexico

Brazil  
Turkey  
GCC Countries  
Egypt

#### Chapter Outline

Chapter 1: Defines the scope of the report and presents an executive summary of market segments (by Type, by Application, , etc.), including the size of each segment and its future growth potential. It offers a high-level view of the current market and its likely evolution in the short, medium, and long term.

Chapter 2: Provides a detailed analysis of the competitive landscape for Ultrasonic Wafer Inspection Equipment manufacturers, including prices, production, value-based market shares, latest development plans, and information on mergers and acquisitions.

Chapter 3: Examines Ultrasonic Wafer Inspection Equipment production/output and value by region and country, providing a quantitative assessment of market size and growth potential for each region over the next six years.

Chapter 4: Analyzes Ultrasonic Wafer Inspection Equipment consumption at the regional and country levels. It quantifies market size and growth potential for each region and its key countries, and outlines market development, outlook, addressable space, and national production.

Chapter 5: Analyzes market segments by Type, covering the size and growth potential of each segment to help readers identify “blue ocean” opportunities.

Chapter 6: Analyzes market segments by Application, covering the size and growth potential of each segment to help readers identify “blue ocean” opportunities in downstream markets.

Chapter 7: Profiles key players, detailing the fundamentals of major companies, including product production/output, value, price, gross margin, product portfolio/introductions, and recent developments.

Chapter 8: Reviews the industry value chain, including upstream and downstream segments.

Chapter 9: Discusses market dynamics and recent developments, including drivers, restraints, challenges and risks for manufacturers, U.S. Tariffs and relevant policy analysis.

Chapter 10: Summarizes the key findings and conclusions of the report.